



VMDSEMI

VFTA010R039NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	3.9mΩ@10V	145A

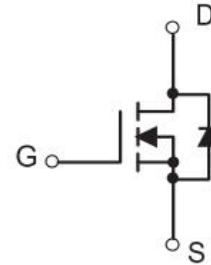


Figure 1 Symbol of VFTA010R039NA

Features

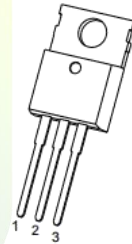
- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switch Application

Package Type

1. GATE
2. DRAIN
3. SOURCE



TO-220-3L-C

Figure 2 Package Type of VFTA010R039NA

Ordering Information

Product Name	Package
VFTA010R039NA	TO-220-3L-C

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1} $T_C = 25\text{ °C}$	I_D	145	A
Continuous Drain Current ^{Note1} $T_C = 100\text{ °C}$		102	
Pulsed Drain Current ^{Note2}	I_{DM}	580	
Avalanche Current ^{Note3}	I_{AS}	27	
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	182	mJ
Total Power Dissipation ^{Note5} $T_C = 25\text{ °C}$	P_D	417	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		60		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		0.3		°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	2.9	4.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		3.0	3.9	mΩ
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=5V, I_D=20A$		50		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=50V$		5673		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		1480		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		69		pF
Total Gate Charge	Q_g	$V_{DS}=50V$		80.9		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		25.3		
Gate-Drain Charge	Q_{gd}	$I_D=20A$		16.0		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		2.9		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		31		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		22		
Turn-off Delay Time	$t_{d(off)}$	$R_L=2.5\Omega$		44		
Turn-off Fall Time	t_f	$R_G=3\Omega$		28		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=20A$			1.2	V

Notes :

- The maximum current rating is limited by package. And device mounted on a large heatsink.
- Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- EAS condition: $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$. And device mounted on a large heatsink
- Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

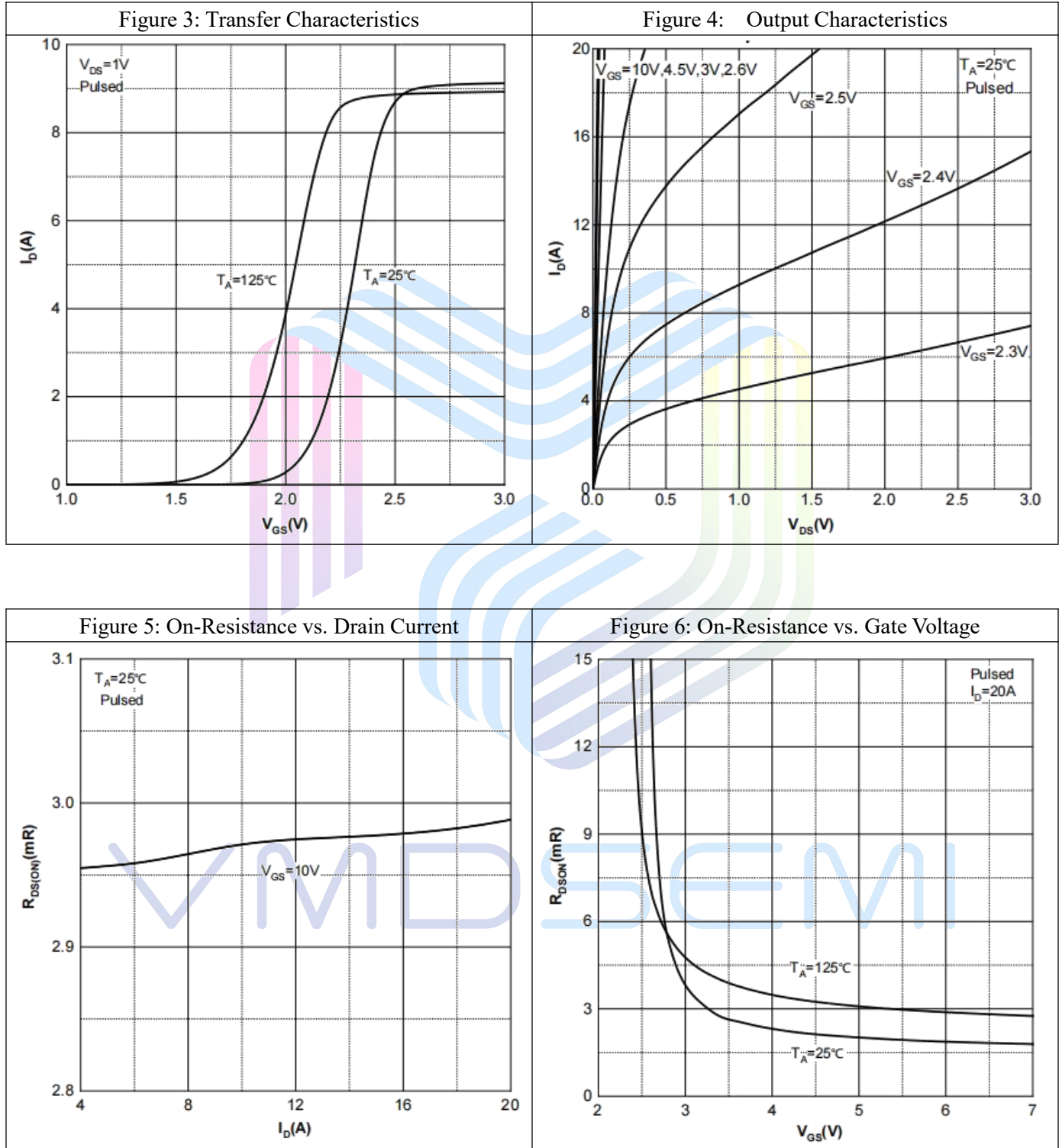
Typical Performance Characteristics


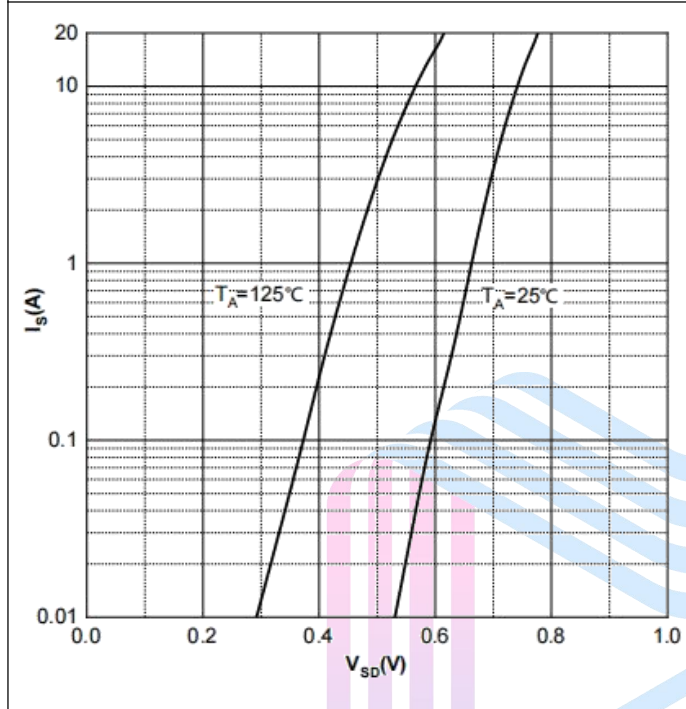
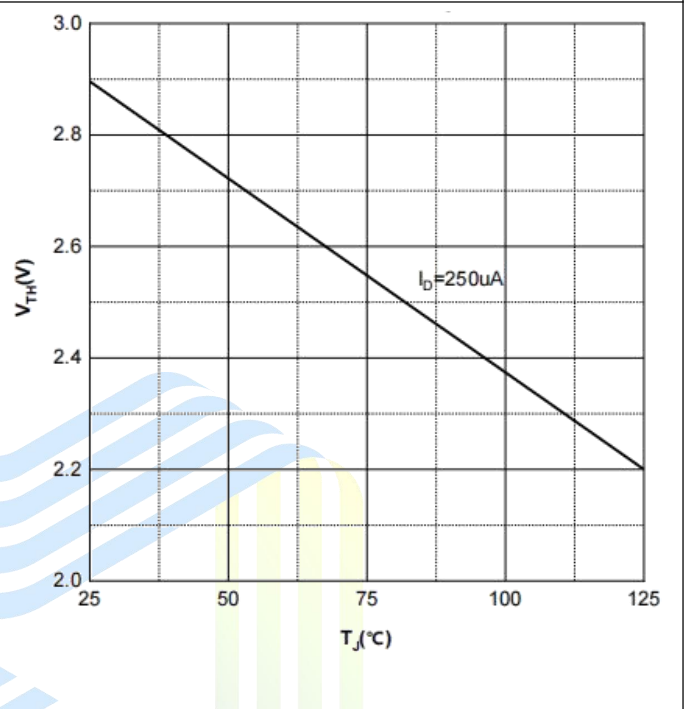
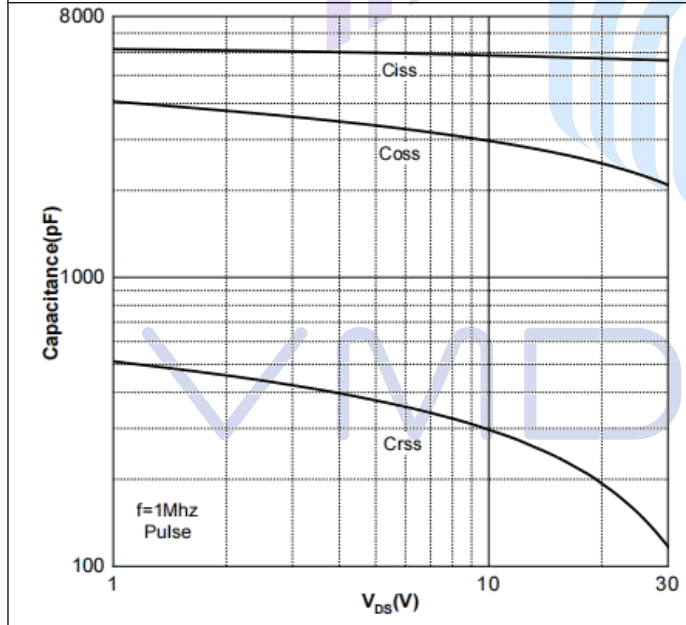
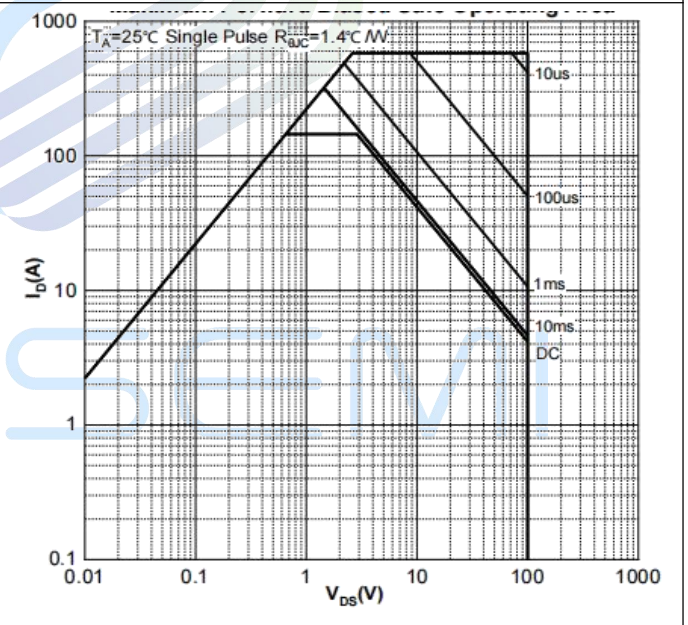
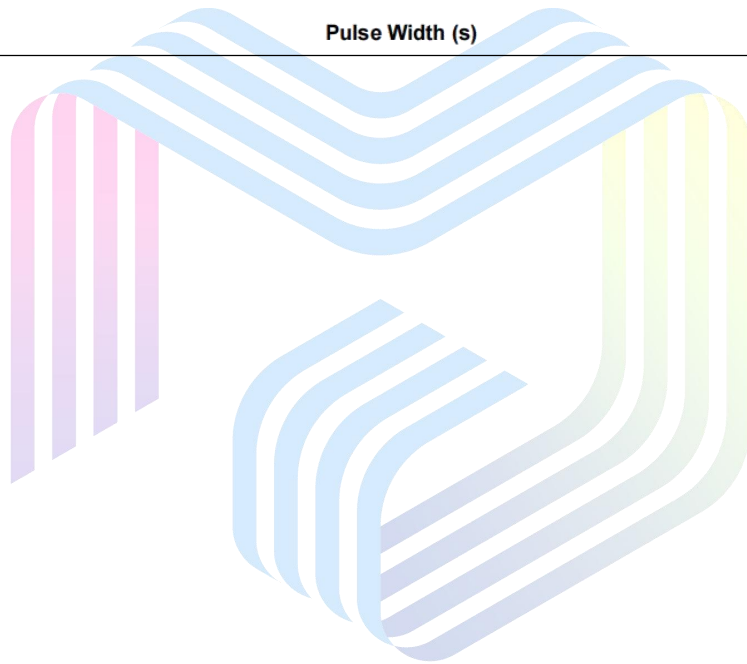
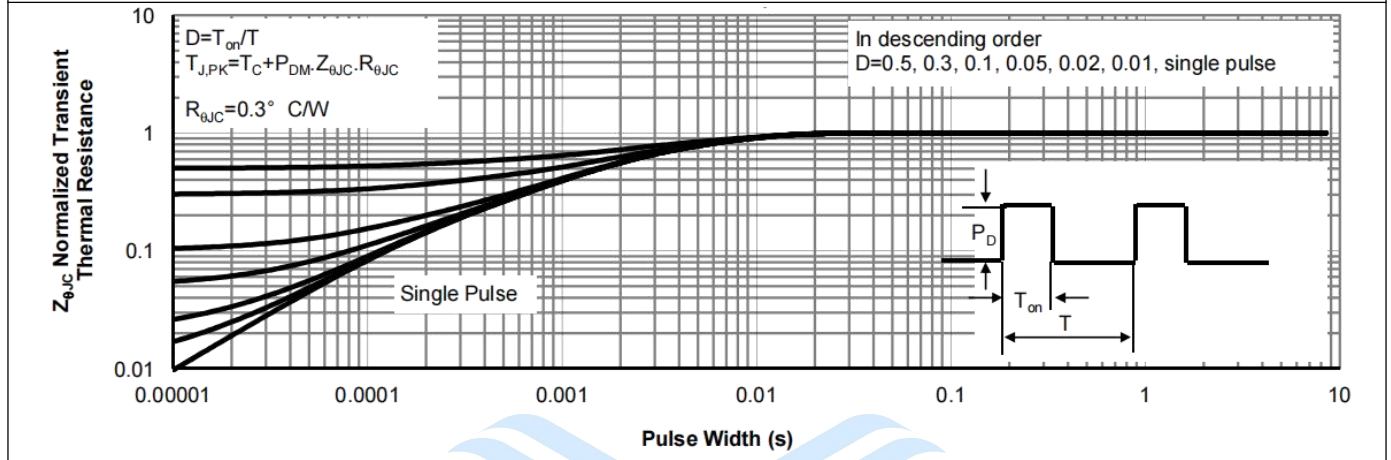
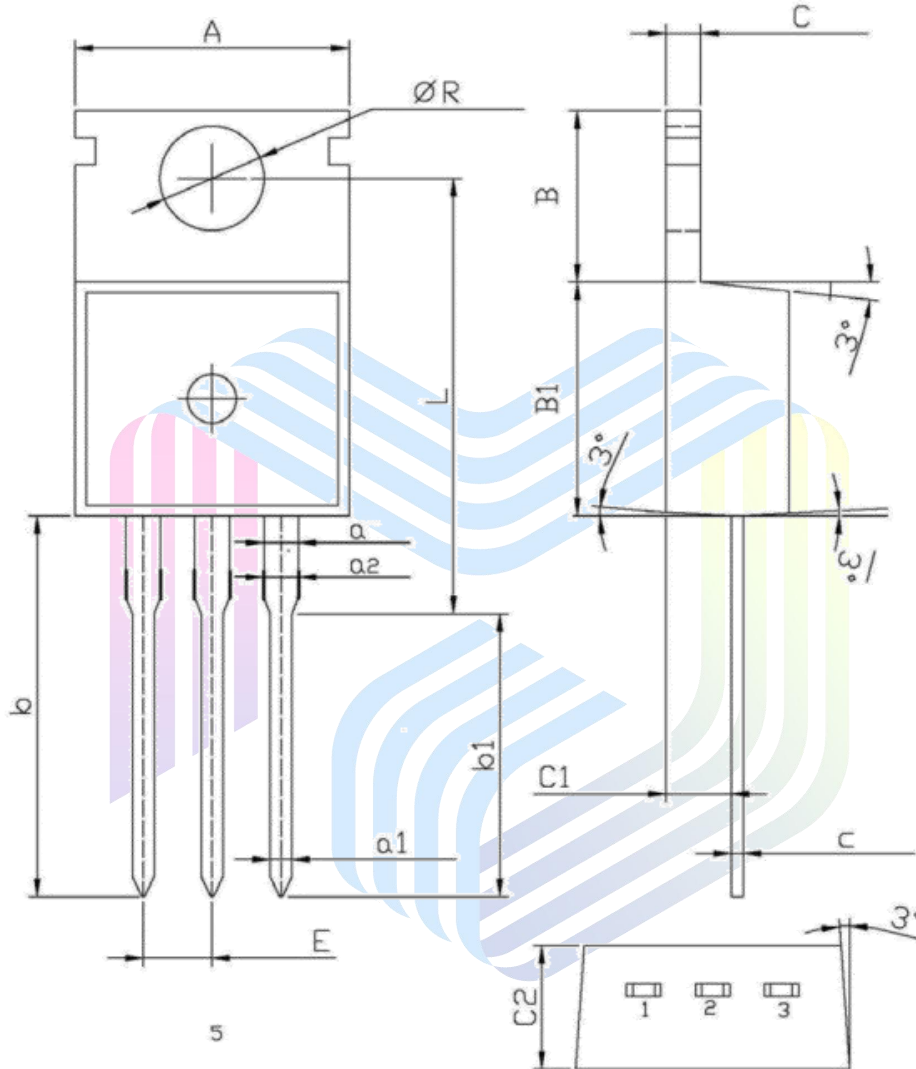
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance


VMDSEMI

Mechanical Dimensions:
TO-220-3L-C Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.800	10.200	0.386	0.402
R	3.560	3.640	0.140	0.143
L	15.700	16.100	0.618	0.634
b	12.600	13.600	0.496	0.535
b1	9.600	10.600	0.378	0.417
a	1.220	1.320	0.048	0.052
E	2.340	2.740	0.092	0.108
a2	1.250	1.450	0.049	0.057
C	1.200	1.400	0.047	0.055
B	6.300	6.700	0.248	0.264
B1	9.000	9.400	0.354	0.370
C1	2.200	2.600	0.087	0.102
a1	0.700	0.900	0.028	0.035
c	0.400	0.600	0.016	0.024
C2	4.300	4.700	0.169	0.185

NOTICE

Hangzhou VMD Semiconductor Co., Ltd (VMD) reserves the right to make changes without notice in order to improve reliability, function or design and to discontinue any product or service without notice. Customers should obtain the latest relevant information before orders and should verify that such information is current and complete. All products are sold subject to VMD's terms and conditions supplied at the time of order acknowledgement.

VMD, its affiliates, agents, and employees, and all persons acting on its or their behalf, disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

VMD disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify VMD's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

VMD warrants performance of its hardware products to the specifications at the time of sale, testing, reliability and quality control are used to the extent VMD deems necessary to support this warrantee. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

VMD does not assume any liability arising from the use of any product or circuit designs described herein. Customers are responsible for their products and applications using VMD's components. To minimize risk, customers must provide adequate design and operating safeguards.

VMD does not warrant or convey any license to any intellectual property rights either expressed or implied under its patent rights, nor the rights of others. Reproduction of information in VMD's data sheets or data books is permissible only if reproduction is without modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice.

VMD is not responsible or liable for such altered documentation. Resale of VMD's products with statements different from or beyond the parameters stated by VMD for that product or service voids all express or implied warrantees for the associated VMD product or service and is an unfair and deceptive business practice.

All Rights Reserved.





Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Shenzhen

Shenzhen Sales office
Room 4A15, Block AB, Tianxiang Building,
Chegongmiao , Futian District, Shenzhen, P.R of China
Tel: +86-0755- 82570682

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China